

**General Features**

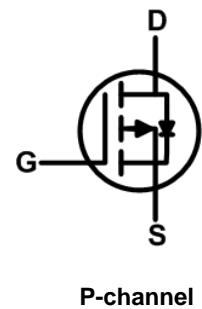
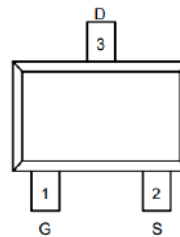
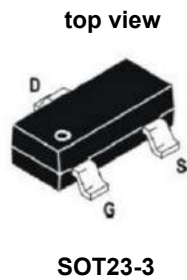
- $R_{DS(ON)} < 20m\Omega$ @ $V_{GS} = -10V$
 $R_{DS(ON)} < 33m\Omega$ @ $V_{GS} = -4.5V$
- High Power and Current Handling Capability
- Lead Free Product is Acquired
- Surface Mount Package

Product Summary

VDS	-30	V
$R_{DS(on),max.}@ V_{GS}=10 V$	20	m Ω
ID	-9	A

Applications

- PWM Applications
- Load Switch
- Power Management

**Absolute Maximum Ratings** ($T_C=25^\circ C$ unless otherwise specified)

Symbol	Parameter	Max.	Units	
V_{DSS}	Drain-Source Voltage	-30	V	
V_{GSS}	Gate-Source Voltage	± 12	V	
I_D	Continuous Drain Current	$T_C = 25^\circ C$	-9	A
		$T_C = 100^\circ C$	-5	
I_{DM}	Pulsed Drain Current ^{note1}	-15	A	
P_D	Power Dissipation	$T_C = 25^\circ C$	1.8	W
$R_{\theta JC}$	Thermal Resistance, Junction to Ambient	6.9	$^\circ C/W$	
T_J, T_{STG}	Operating and Storage Temperature Range	-55 to +150	$^\circ C$	

**Electrical Characteristics** ($T_C=25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Off Characteristic						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D = -250\mu A$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30V, V_{GS} = 0V,$	-	-	-1	μA
I_{GSS}	Gate to Body Leakage Current	$V_{DS} = 0V, V_{GS} = \pm 12V$	-	-	± 100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu A$	-1.0	-1.6	-2.5	V
$R_{DS(on)}$	Static Drain-Source on-Resistance <small>note2</small>	$V_{GS} = -10V, I_D = -5A$	-	16	20	m Ω
		$V_{GS} = -4.5V, I_D = -3.0A$	-	23	33	
g_{FS}	Forward Transconductance	$V_{DS} = -5V, I_D = -5.0A$	20	-	-	S
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{DS} = -15V, V_{GS} = 0V,$ $f = 1.0MHz$	-	1300	-	pF
C_{oss}	Output Capacitance		-	240	-	pF
C_{rss}	Reverse Transfer Capacitance		-	95	-	pF
Q_g	Total Gate Charge	$V_{DS} = -15V, I_D = -5A,$ $V_{GS} = -1.0V$	-	20	50	nC
Q_{gs}	Gate-Source Charge		-	4	-	nC
Q_{gd}	Gate-Drain("Miller") Charge		-	6	-	nC
Switching Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DS} = -15V, I_D = -4A,$ $R_{GEN} = 2.5\Omega, V_{GS} = -1.0V$	-	11	-	ns
t_r	Turn-on Rise Time		-	18	-	ns
$t_{d(off)}$	Turn-off Delay Time		-	30	-	ns
t_f	Turn-off Fall Time		-	10	-	ns
Drain-Source Diode Characteristics and Maximum Ratings						
I_S	Maximum Continuous Drain to Source Diode Forward Current		-	-	-7	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-10	A
V_{SD}	Drain to Source Diode Forward Voltage	$V_{GS} = 0V, I_S = -5A$	-	-	-1.2	V

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

2. Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$



■ Typical Performance Characteristics

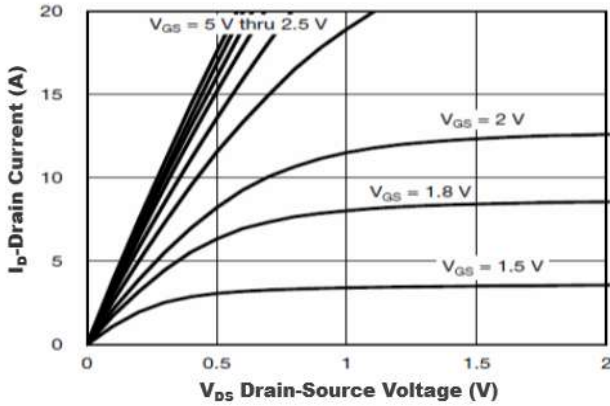


Figure1. Output Characteristics

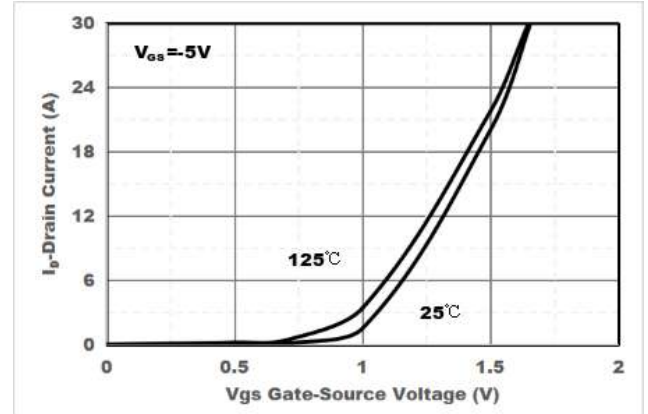


Figure2. Transfer Characteristics

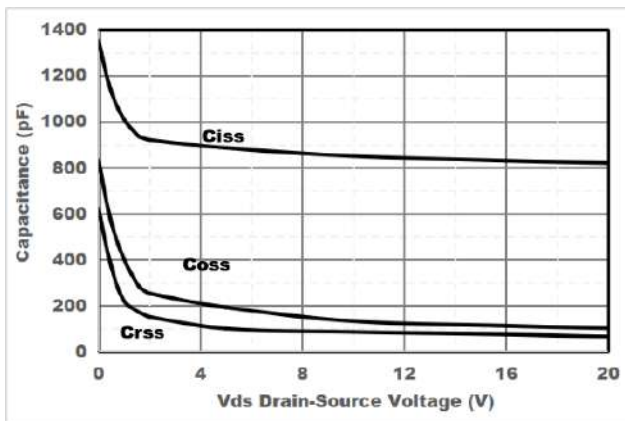


Figure3. Capacitance Characteristics

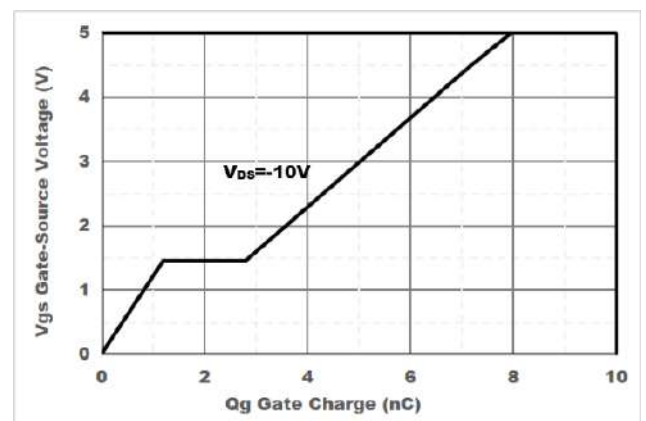


Figure4. Gate Charge

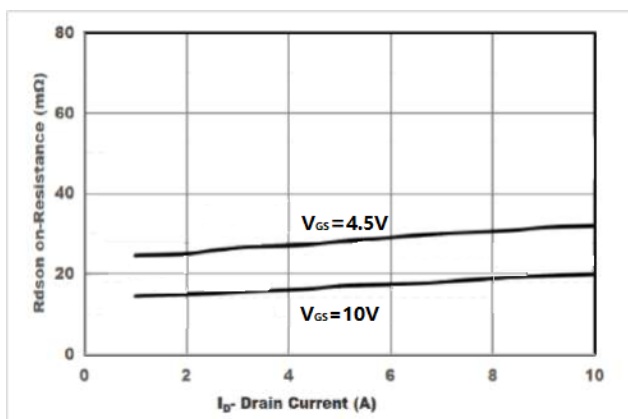


Figure5. Drain-Source on Resistance

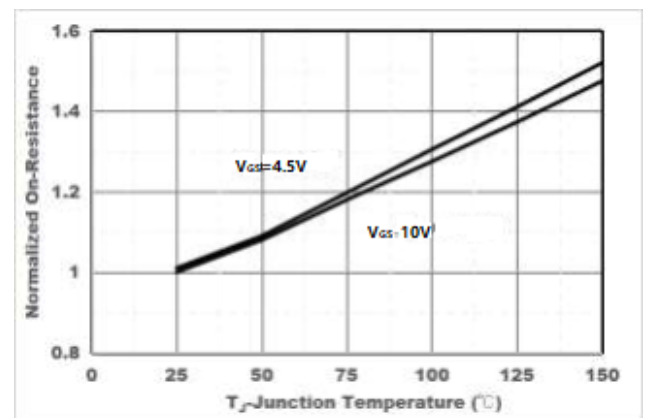


Figure6. Drain-Source on Resistance

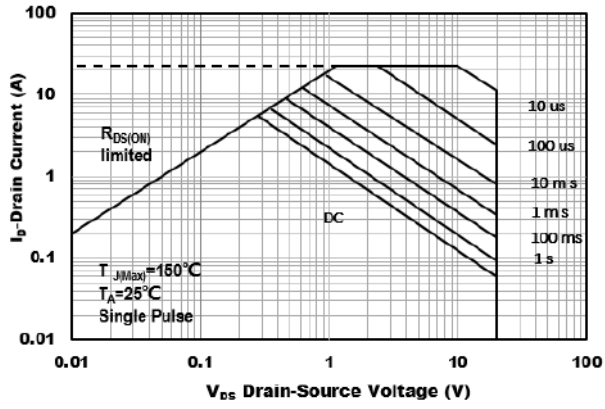


Figure7. Safe Operation Area

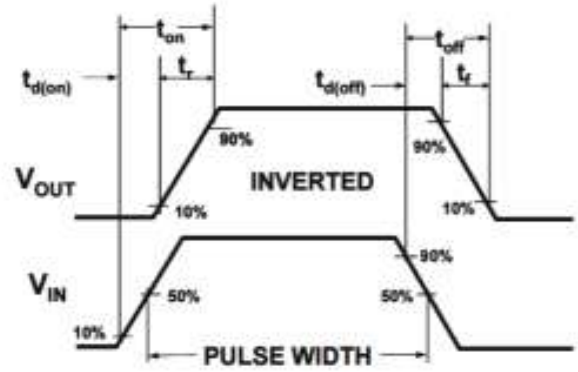
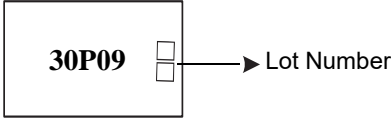


Figure8. Switching wave

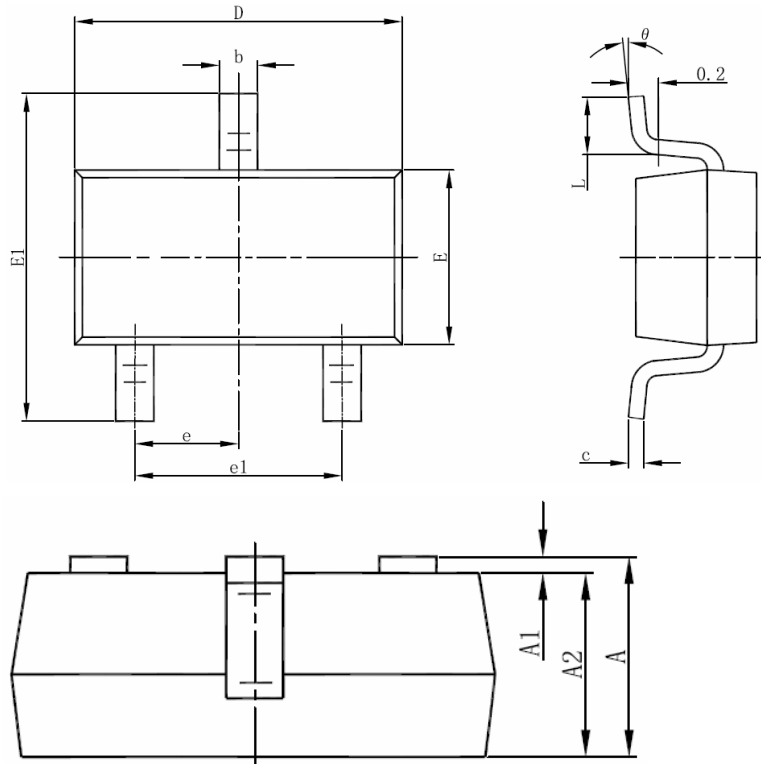
Ordering and Marking Information

Ordering Device No	Marking	Package	Packing	Quantity
ASDM30P09-ZB-R	30P09	SOT23-3	Tape&Reel	3000

PACKAGE	MARKING
SOT23-3	 <p>The marking diagram shows a rectangular box containing the text '30P09' followed by two small squares. An arrow points from the second square to the text 'Lot Number'.</p>

<p>ASDM3404-ZB- R</p> <ul style="list-style-type: none"> └── 1 Packing Type └── 2 Package Type 	<ul style="list-style-type: none"> 1 T:Tube,R:Tape Reel 2 ZB: SOT23-3
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SOT-23-3L PACKAGE INFORMATION



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D	2.820	3.020	0.111	0.119
E	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC)		0.037(BSC)	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

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